

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp	
S1	31	(("4665492") or ("5121329") or ("5134569") or ("5141680") or ("5173220") or ("5216616") or ("5260009") or ("5264061") or ("5340433") or ("5476211") or ("5484314") or ("5705117") or ("5772451") or ("5820014") or ("5832601") or ("5852871") or ("5864946") or ("5884398") or ("5912046") or ("5998228") or ("6133355") or ("6193923") or ("6270335") or ("6305769") or ("6347257") or ("6352668") or ("6406531") or ("6490496") or ("6492651") or ("6532394") or ("6508971")).PN.	USPAT	OR	OFF		2005/10/24 11:11
S2	1125	farnworth.in. and contact	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/19 10:37	
S3	1022	S2 and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/19 10:37	
S4	331	S3 and coating	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/19 10:37	
S5	40	S4 and stereolithographic\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/19 10:38	
S6	222	semiconductor and (superimposed same adhered same layer) and contact	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/19 11:45	

S7	1	S6 and sacrific\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/19 11:45
S8	49	(("5280236") or ("6235622") or ("4767591") or ("4780086") or ("4965865") or ("4968589") or ("5807763") or ("5838159") or ("5942911") or ("5951323") or ("5986283") or ("6057918") or ("6174175") or ("6221750") or ("6221750") or ("6245444") or ("6336269") or ("6380554") or ("6468098") or ("4389551") or ("5831441") or ("6005405") or ("3920003") or ("4259635") or ("4301338") or ("4326766") or ("4333238") or ("4339714") or ("4341568") or ("4357821") or ("4375723") or ("4381650") or ("4426960") or ("4461077") or ("4490913") or ("4492831") or ("4496903") or ("4525016") or ("4566343") or ("4571473") or ("4583101") or ("4588249") or ("4607525") or ("4632485") or ("4761979") or ("4763507") or ("4766329") or ("4775328") or ("4803373") or ("4853624")).PN.	USPAT	OR	OFF	2005/10/24 10:42
S9	409	(439/886).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/24 10:42
S10	4	439/886.ccls. and (core same (polymer or dielectric))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 15:33
S11	10	("3042591" "3475186" "4529257" "4532152" "4604799" "4737118" "4820170" "4838799").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/24 10:45
S12	17	("4969842").URPN.	USPAT	OR	ON	2005/10/24 10:50
S13	28	439/886.ccls. and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 11:01

S14	1062	semiconductor and (core same (polymer or dielectric)) and contact and (conductive with coat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 11:12
S15	247	semiconductor and ((core same (polymer or dielectric)) same contact) and (conductive with coat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 11:20
S16	4	(semiconductor and ((core same (polymer or dielectric)) same contact) and (conductive with coats\$3)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 11:13
S17	35	S15 and filament	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 11:21
S18	2	("6589819").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/24 13:09
S19	69	439/886.ccls. and (polymer or dielectric)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 13:51
S20	1050	"438"/\$.ccls. and (core same (polymer or dielectric))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 15:06
S21	23	S20 and filament	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 15:02

S22	906	S20 and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 15:02
S23	21	S22 and filament	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 15:03
S24	657	"438"/\$.ccls. and (core with (polymer or dielectric))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 15:06
S25	560	S24 and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 15:07
S26	10	S25 and filament	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 15:07
S27	1404	(438/127).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/24 15:14
S28	21	438/127.ccls. and (core with (polymer or dielectric))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 15:51
S29	7	contact and semiconductor and core and polymer and conductive and coat\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 15:52

S30	0	(contact and semiconductor and core and polymer and condutive and coat\$3).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 15:52
S31	0	(contact and semiconductor and core and dielectric and condutive and coat\$3).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 15:52
S32	7	(contact and semiconductor and core and dielectric and condutive and coat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 16:10
S33	489	(439/862).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/24 16:10